INSTALL LABEL IN SILKSCREEN BOX AFTER FINAL WASH. TEXT SHALL BE 8 PT FONT. TEXT SHALL BE PER THE LABEL TABLE IN THE PDF SCHEMATIC.

These assemblies are ESD sensitive, ESD precautions shall be observed.

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE

BOARD #: ISE3017  REVISION: E2  SUN REV: Not In VersionControl

IGNORE -> Assembly top

PLOT NAME = Top Assembly Drawing  GENERATED: 10/1/2014 4:24:18 PM  TEXAS INSTRUMENTS
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE

BOARD #: ISE3017
REV: E2
SUN REV: Not In VersionControl

ignore -> assembly bottom

plot name = Bottom Assembly Drawing

generated: 10/1/2014 4:24:18 PM
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